



## Initial Product/Process Change Notification

Document #:IPC23161X1

Issue Date:27 Feb 2022

<b>Title of Change:</b>	Update to IPCN23161X - Minigates (3.3V) TPSCO Wafer Qualification with BOM change in US8 Package, push out FPCN implementation		
<b>Proposed First Ship date:</b>	To be defined during FPCN release		
<b>Contact Information:</b>	Contact your local onsemi Sales Office or <a href="mailto:logic.fpcn@onsemi.com">logic.fpcn@onsemi.com</a>		
<b>PCN Samples Contact:</b>	Contact your local onsemi Sales Office. Sample requests are to be submitted no later than 30 days from the date of first notification, Initial PCN or Final PCN, for this change. Samples delivery timing will be subject to request date, sample quantity and special customer packing/label requirements.		
<b>Type of Notification:</b>	This is an Initial Product/Process Change Notification (IPCN) sent to customers. An IPCN is an advance notification about an upcoming change and contains general information regarding the change details and devices affected. It also contains the preliminary reliability qualification plan. The completed qualification and characterization data will be included in the Final Product/Process Change Notification (FPCN). This IPCN notification will be followed by a Final Product/Process Change Notification (FPCN) at least 90 days prior to implementation of the change. In case of questions, contact < <a href="mailto:PCN.Support@onsemi.com">PCN.Support@onsemi.com</a> >		
<b>Marking of Parts/ Traceability of Change:</b>	The CS code on the label will be changed from US to JP.		
<b>Change Category:</b>	Assembly Change, Wafer Fab Change, Test Change		
<b>Change Sub-Category(s):</b>	Shipping/Packaging/Marking, Datasheet/Product Doc change, Material Change, Manufacturing Process Change, Manufacturing Site Transfer		
<b>Sites Affected:</b>			
<b>onsemi Sites</b>		<b>External Foundry/Subcon Sites</b>	
onsemi Maine, United States		HANA Semiconductor, Thailand	
		STARS Microelectronics, Thailand	
		Towerjazz Semiconductor, Japan (Toyama)	
<b>Description and Purpose:</b>			
This update IPCN23161X1 is released to inform customers that we are pushing out the implementation of the change described in IPCN23161X due to wafer fab constraint Towerjazz Semiconductor TPSCo. All the affected parts will continue be supplied using the existing qualified site and BOM. Actual Proposed First Ship date or implementation timing will be defined on the FPCN once released.			
<b>Qualification Plan:</b>			
<b>QV DEVICE NAME: NC7SV74K8X</b>			
<b>RMS: S60403</b>			
<b>PACKAGE: US8</b>			
<b>Test</b>	<b>Specification</b>	<b>Condition</b>	<b>Interval</b>
HTOL	JESD22-A108	Ta=125°C, 120 % max rated Vcc	2016 hours
HTSL	JESD22-A103	Ta= 150°C	2016 hours
TC + PC	JESD22-A104	Ta= -65°C to +150°C	1000 cycles
HAST + PC	JESD22-A110	130°C, 85% RH, 18.8psig, bias	192 hours



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uHAST + PC	JESD22-A118	130°C, 85% RH, 18.8psig, unbiased	96 hours
PC	J-STD-020 JESD-A113	MSL 1 @ 260°C	-
RSH	JESD22- B106	Ta = 265C, 10 sec	-

### List of Affected Parts:

**Note:** Only the standard (off the shelf) part numbers are listed in the parts list. Any custom parts affected by this PCN are shown in the customer specific PCN addendum in the PCN email notification, or on the [\*\*PCN Customized Portal\*\*](#).

Part Number	Qualification Vehicle
NC7NP34K8X	NC7SV74K8X
NC7WV125K8X	NC7SV74K8X
NC7WP32K8X	NC7SV74K8X
NC7WP08K8X	NC7SV74K8X
NC7WP02K8X	NC7SV74K8X
NC7WP00K8X	NC7SV74K8X
NC7SV74K8X	NC7SV74K8X
NC7WP125K8X	NC7SV74K8X
NC7NP14K8X	NC7SV74K8X
NC7SP74K8X	NC7SV74K8X